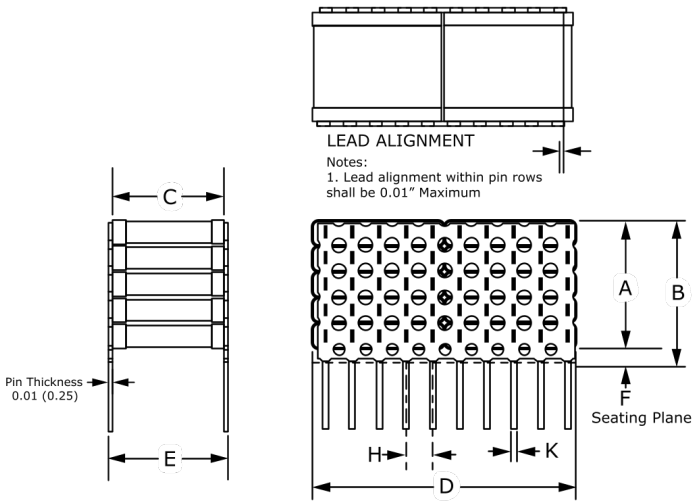
L1GN30B125KH10

KPS-MCC Indust C0G HT200C, Ceramic, 1.2 uF, 10%, 630 VDC, C0G



Click here for the 3D model.

Dimensions

D	25.64mm +/-0.635mm
L	6.35mm MIN
H	2.54mm NOM
F	1.397mm +/-0.25mm
A	13.46mm MAX
B	15.238mm MAX
C	11.43mm +/-0.635mm
E	12.7mm MAX
K	0.5mm NOM

Packaging Specifications

Packaging	Waffle, Box
Packaging Quantity	16

General Information

Series	KPS-MCC Indust C0G HT200C
Style	Leaded Stacked Chip
Description	Low ESR, Stacked Ceramic Chips
Features	200C, Low ESR, High Thermal Stability, Bulk Capacitance
RoHS	No
Prop 65	⚠ **WARNING:** Cancer and reproductive harm - http://www.p65warnings.ca.gov.
Termination	60/40 Solder Coated
Lead	Straight Leads
AEC-Q200	No
Notes	Number of chips in this stack: 10.

Specifications

Capacitance	1.2 uF
Capacitance Tolerance	10%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	819 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	C0G
Dissipation Factor	0.1% 1 kHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	830 MOhms

单击下面可查看定价，库存，交付和生命周期等信息

>>KEMET(基美)